

(19) World Intellectual Property  
Organization  
International Bureau



(43) International Publication Date  
17 February 2005 (17.02.2005)

PCT

(10) International Publication Number  
**WO 2005/014623 A3**

(51) International Patent Classification<sup>7</sup>: **C07K 19/00**,  
14/705, 14/78, 14/52, C12N 9/64, A61K 38/17, 38/43,  
38/19, 38/39

MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG,  
PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM,  
TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM,  
ZW.

(21) International Application Number:  
PCT/DK2004/000527

(84) Designated States (unless otherwise indicated, for every  
kind of regional protection available): ARIPO (BW, GH,  
GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM,  
ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM),  
European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI,  
FR, GB, GR, HU, IE, IT, LU, MC, NL, PL, PT, RO, SE, SI,  
SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ,  
GW, ML, MR, NE, SN, TD, TG).

(22) International Filing Date: 6 August 2004 (06.08.2004)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:  
PA 2003 01141 7 August 2003 (07.08.2003) DK  
PA 2004 00814 25 May 2004 (25.05.2004) DK

**Declaration under Rule 4.17:**

— as to applicant's entitlement to apply for and be granted  
a patent (Rule 4.17(ii)) for the following designations AE,  
AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ,  
CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE,  
EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS,  
JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA,  
MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM,  
PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ,  
TM, TN, TR, TT, TZ, UA, UG, UZ, VC, VN, YU, ZA, ZM,  
ZW, ARIPO patent (BW, GH, GM, KE, LS, MW, MZ, NA,  
SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian patent (AM, AZ,  
BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE,  
BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE,  
IT, LU, MC, NL, PL, PT, RO, SE, SI, SK, TR), OAPI patent  
(BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE,  
SN, TD, TG)

(71) Applicant (for all designated States except US): **ENKAM  
PHARMACEUTICALS A/S [DK/DK]**; Fruebjergvej 3,  
DK-2100 Copenhagen Ø (DK).

(72) Inventors; and

(75) Inventors/Applicants (for US only): **ALBRECHTSEN**,  
Morten [DK/DK]; Høstvej 7, DK-2920 Charlotten-  
lund (DK). **BOCK**, Elisabeth [DK/DK]; Tonysvej 20,  
DK-2920 Charlottenlund (DK). **BEREZIN**, Vladimir  
[UA/DK]; Nørrebrogade 223, 1.th., DK-2200 Copenhagen  
N (DK). **HOLM**, Arne [DK/DK]; Skodsborgparken 20,  
2.th., DK-2942 Skodsborg (DK).

(74) Agent: **HØIBERG A/S**; St. Kongensgade 59A, DK-1264  
Copenhagen K (DK).

**Published:**

— with international search report

(81) Designated States (unless otherwise indicated, for every  
kind of national protection available): AE, AG, AL, AM,  
AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN,  
CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI,  
GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE,  
KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD,

(88) Date of publication of the international search report:  
9 September 2005

For two-letter codes and other abbreviations, refer to the "Guid-  
ance Notes on Codes and Abbreviations" appearing at the begin-  
ning of each regular issue of the PCT Gazette.

(54) Title: COMPOUNDS COMPRISING LPA

(57) Abstract: The present invention relates to new peptide compounds capable of binding to fibroblast growth factor receptor (FGFR), said compounds comprising two individual amino acid sequences, wherein at least one of the two amino acid sequences is capable of binding to FGFR. The invention discloses the amino acid sequences of the compounds and features pharmaceutical compositions comprising thereof. Invention also relates to uses of the compounds and pharmaceutical compositions comprising thereof for the treatment or prevention of different pathological conditions, wherein FGFR plays a role in pathology and/or recovery from the disease. New peptide compounds of the invention are obtainable by the ligand presenting assembly (LPA) method.

WO 2005/014623 A3